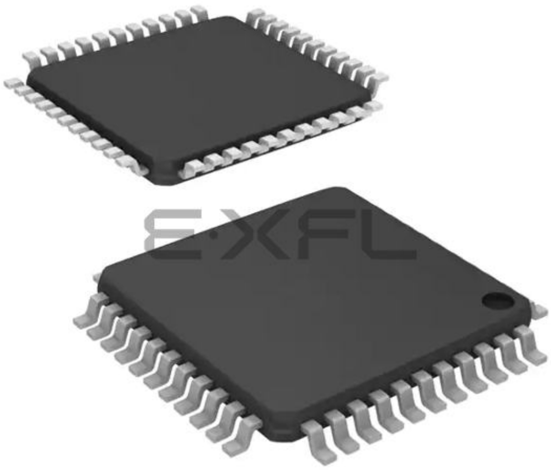


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DCI, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b; D/A 2x16b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64gp804-e-pt

TABLE 4-37: FUNDAMENTAL ADDRESSING MODES SUPPORTED

Addressing Mode	Description
File Register Direct	The address of the file register is specified explicitly.
Register Direct	The contents of a register are accessed directly.
Register Indirect	The contents of Wn forms the Effective Address (EA).
Register Indirect Post-Modified	The contents of Wn forms the EA. Wn is post-modified (incremented or decremented) by a constant value.
Register Indirect Pre-Modified	Wn is pre-modified (incremented or decremented) by a signed constant value to form the EA.
Register Indirect with Register Offset (Register Indexed)	The sum of Wn and Wb forms the EA.
Register Indirect with Literal Offset	The sum of Wn and a literal forms the EA.

4.5.3 MOVE AND ACCUMULATOR INSTRUCTIONS

Move instructions and the DSP accumulator class of instructions provide a greater degree of addressing flexibility than other instructions. In addition to the addressing modes supported by most MCU instructions, move and accumulator instructions also support Register Indirect with Register Offset Addressing mode, also referred to as Register Indexed mode.

> **Note:** For the `MOV` instructions, the addressing mode specified in the instruction can differ for the source and destination EA. However, the 4-bit Wb (Register Offset) field is shared by both source and destination (but typically only used by one).

In summary, the following addressing modes are supported by move and accumulator instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-modified
- Register Indirect Pre-modified
- Register Indirect with Register Offset (Indexed)
- Register Indirect with Literal Offset
- 8-bit Literal
- 16-bit Literal

> **Note:** Not all instructions support all the addressing modes given above. Individual instructions may support different subsets of these addressing modes.

4.5.4 `MAC` INSTRUCTIONS

The dual source operand DSP instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MPY`, `MPY.N`, `MOVSAC` and `MSC`), also referred to as `MAC` instructions, use a simplified set of addressing modes to allow the user application to effectively manipulate the data pointers through register indirect tables.

The two-source operand prefetch registers must be members of the set {W8, W9, W10, W11}. For data reads, W8 and W9 are always directed to the X RAGU, and W10 and W11 are always directed to the Y AGU. The effective addresses generated (before and after modification) must, therefore, be valid addresses within X data space for W8 and W9 and Y data space for W10 and W11.

> **Note:** Register Indirect with Register Offset Addressing mode is available only for W9 (in X space) and W11 (in Y space).

In summary, the following addressing modes are supported by the `MAC` class of instructions:

- Register Indirect
- Register Indirect Post-Modified by 2
- Register Indirect Post-Modified by 4
- Register Indirect Post-Modified by 6
- Register Indirect with Register Offset (Indexed)

4.5.5 OTHER INSTRUCTIONS

Besides the addressing modes outlined previously, some instructions use literal constants of various sizes. For example, `BRA` (branch) instructions use 16-bit signed literals to specify the branch destination directly, whereas the `DISI` instruction uses a 14-bit unsigned literal field. In some instructions, such as `ADD Acc`, the source of an operand or result is implied by the opcode itself. Certain operations, such as `NOP`, do not have any operands.

6.0 RESETS

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 8. "Reset"** (DS70192) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Reset module combines all reset sources and controls the device Master Reset Signal, SYSRST. The following is a list of device Reset sources:

- POR: Power-on Reset
- BOR: Brown-out Reset
- MCLR: Master Clear Pin Reset
- SWR: `RESET` Instruction
- WDTO: Watchdog Timer Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Condition Device Reset
  - Illegal Opcode Reset
  - Uninitialized W Register Reset
  - Security Reset

A simplified block diagram of the Reset module is shown in Figure 6-1.

Any active source of reset will make the SYSRST signal active. On system Reset, some of the registers associated with the CPU and peripherals are forced to a known Reset state and some are unaffected.

> **Note:** Refer to the specific peripheral section or **Section 3.0 "CPU"** of this manual for register Reset states.

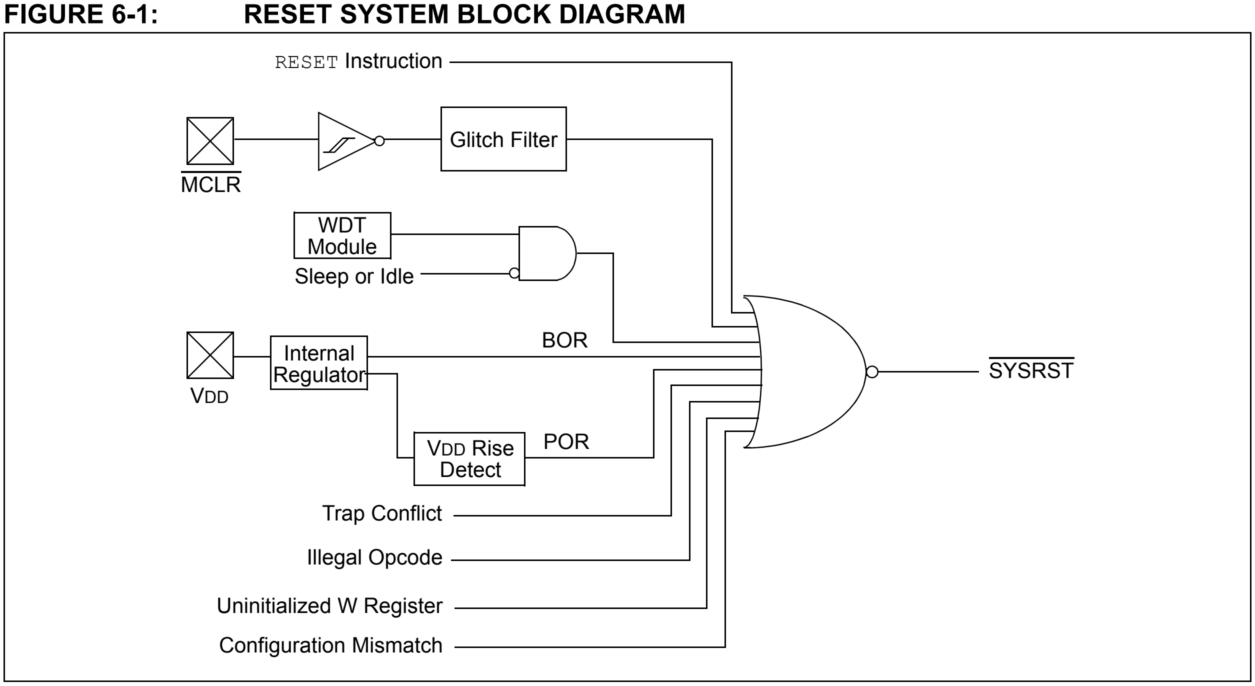
All types of device Reset sets a corresponding status bit in the RCON register to indicate the type of Reset (see Register 6-1).

A POR clears all the bits, except for the POR bit (RCON<0>), that are set. The user application can set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software does not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this manual.

> **Note:** The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset is meaningful.

FIGURE 6-1: RESET SYSTEM BLOCK DIAGRAM



REGISTER 6-1: RCON: RESET CONTROL REGISTER[1] (CONTINUED)

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 9-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3) (CONTINUED)

bit 3	**CF:** Clock Fail Detect bit (read/clear by application) 1 = FSCM has detected clock failure 0 = FSCM has not detected clock failure
bit 2	**Unimplemented:** Read as '0'
bit 1	**LPOSCEN:** Secondary (LP) Oscillator Enable bit 1 = Enable secondary oscillator 0 = Disable secondary oscillator
bit 0	**OSWEN:** Oscillator Switch Enable bit 1 = Request oscillator switch to selection specified by NOSC<2:0> bits 0 = Oscillator switch is complete

Note 1: Writes to this register require an unlock sequence. Refer to **Section 39. "Oscillator (Part III)"** (DS70216) in the *"dsPIC33F/PIC24H Family Reference Manual"* (available from the Microchip website) for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: This register is reset only on a Power-on Reset (POR).

REGISTER 11-12: RPINR22: PERIPHERAL PIN SELECT INPUT REGISTER 22

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SCK2R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	SDI2R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **SCK2R<4:0>:** Assign SPI2 Clock Input (SCK2) to the corresponding RPn pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as ‘0’

bit 4-0 **SDI2R<4:0>:** Assign SPI2 Data Input (SDI2) to the corresponding RPn pin

11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

15.3 Output Compare Control Register

REGISTER 15-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER (x = 1, 2, 3 OR 4)

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0 HC	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	OCFLT	OCTSEL	OCM<2:0>		
bit 7							bit 0

Legend:	HC = Cleared in Hardware	HS = Set in Hardware	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Stop Output Compare in Idle Mode Control bit
1 = Output Compare x halts in CPU Idle mode
0 = Output Compare x continues to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as '0'

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred
(This bit is only used when OCM<2:0> = 111.)

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for Compare x
0 = Timer2 is the clock source for Compare x

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx, Fault pin enabled
110 = PWM mode on OCx, Fault pin disabled
101 = Initialize OCx pin low, generate continuous output pulses on OCx pin
100 = Initialize OCx pin low, generate single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initialize OCx pin high, compare event forces OCx pin low
001 = Initialize OCx pin low, compare event forces OCx pin high
000 = Output compare channel is disabled

REGISTER 16-3: SPIxCON2: SPIx CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
FRMEN	SPIFSD	FRMPOL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	—	FRMDLY	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **FRMEN:** Framed SPIx Support bit
1 = Framed SPIx support enabled ($\overline{SSx}$ pin used as frame sync pulse input/output)
0 = Framed SPIx support disabled

bit 14 **SPIFSD:** Frame Sync Pulse Direction Control bit
1 = Frame sync pulse input (slave)
0 = Frame sync pulse output (master)

bit 13 **FRMPOL:** Frame Sync Pulse Polarity bit
1 = Frame sync pulse is active-high
0 = Frame sync pulse is active-low

bit 12-2 **Unimplemented:** Read as ‘0’

bit 1 **FRMDLY:** Frame Sync Pulse Edge Select bit
1 = Frame sync pulse coincides with first bit clock
0 = Frame sync pulse precedes first bit clock

bit 0 **Unimplemented:** Read as ‘0’
This bit must not be set to ‘1’ by the user application.

17.0 INTER-INTEGRATED CIRCUIT™ (I^2C™)

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Inter-Integrated Circuit (I^2C) module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard, with a 16-bit interface.

The I^2C module has a 2-pin interface:

- The SCLx pin is clock.
- The SDAx pin is data.

The I^2C module offers the following key features:

- I^2C interface supporting both Master and Slave modes of operation.
- I^2C Slave mode supports 7-bit and 10-bit addressing
- I^2C Master mode supports 7 and 10-bit addressing
- I^2C Port allows bidirectional transfers between master and slaves.
- Serial clock synchronization for I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control).
- I^2C supports multi-master operation, detects bus collision and arbitrates accordingly.

17.1 Operating Modes

The hardware fully implements all the master and slave functions of the I^2C Standard and Fast mode specifications, as well as 7 and 10-bit addressing.

The I^2C module can operate either as a slave or a master on an I^2C bus.

The following types of I^2C operation are supported:

- I^2C slave operation with 7-bit addressing
- I^2C slave operation with 10-bit addressing
- I^2C master operation with 7-bit or 10-bit addressing

For details about the communication sequence in each of these modes, refer to the "*dsPIC33F/PIC24H Family Reference Manual*". Please see the Microchip website (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual chapters.

REGISTER 19-10: CiCFG2: ECAN™ BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH<2:0>		
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH<2:0>			PRSEG<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14 **WAKFIL:** Select CAN bus Line Filter for Wake-up bit
1 = Use CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as ‘0’

bit 10-8 **SEG2PH<2:0>:** Phase Segment 2 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PH bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Segment 1 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

REGISTER 21-2: AD1CON2: ADC1 CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
VCFG<2:0>			—	—	CSCNA	CHPS<1:0>	
bit 15							bit 8

R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS	—	SMPI<3:0>				BUFM	ALTS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **VCFG<2:0>:** Converter Voltage Reference Configuration bits

	ADREF+	ADREF-
000	AVDD	AVSS
001	External VREF+	AVSS
010	AVDD	External VREF-
011	External VREF+	External VREF-
1xx	AVDD	Avss

bit 12-11 **Unimplemented:** Read as ‘0’

bit 10 **CSCNA:** Scan Input Selections for CH0+ during Sample A bit
1 = Scan inputs
0 = Do not scan inputs

bit 9-8 **CHPS<1:0>:** Selects Channels Utilized bits
When AD12B = 1, CHPS<1:0> is: U-0, Unimplemented, Read as ‘0’
1x = Converts CH0, CH1, CH2 and CH3
01 = Converts CH0 and CH1
00 = Converts CH0

bit 7 **BUFS:** Buffer Fill Status bit (only valid when BUFM = 1)
1 = ADC is currently filling buffer 0x8-0xF, user should access data in 0x0-0x7
0 = ADC is currently filling buffer 0x0-0x7, user should access data in 0x8-0xF

bit 6 **Unimplemented:** Read as ‘0’

bit 5-2 **SMPI<3:0>:** Selects Increment Rate for DMA Addresses bits or number of sample/conversion operations per interrupt
1111 = Increments the DMA address or generates interrupt after completion of every 16th sample/conversion operation
1110 = Increments the DMA address or generates interrupt after completion of every 15th sample/conversion operation
•
•
•
0001 = Increments the DMA address after completion of every 2nd sample/conversion operation
0000 = Increments the DMA address after completion of every sample/conversion operation

bit 1 **BUFM:** Buffer Fill Mode Select bit
1 = Starts buffer filling at address 0x0 on first interrupt and 0x8 on next interrupt
0 = Always starts filling buffer at address 0x0

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses channel input selects for Sample A on first sample and Sample B on next sample
0 = Always uses channel input selects for Sample A

24.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note 1: This data sheet summarizes the features of the dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 37. "Real-Time Clock and Calendar (RTCC)"** (DS70301) of the "*dsPIC33F/PIC24H Family Reference Manual*", which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This chapter discusses the Real-Time Clock and Calendar (RTCC) module, available on dsPIC33FJ32GP302/304, dsPIC33FJ64GPX02/X04, and dsPIC33FJ128GPX02/X04 devices, and its operation. The following are some of the key features of this module:

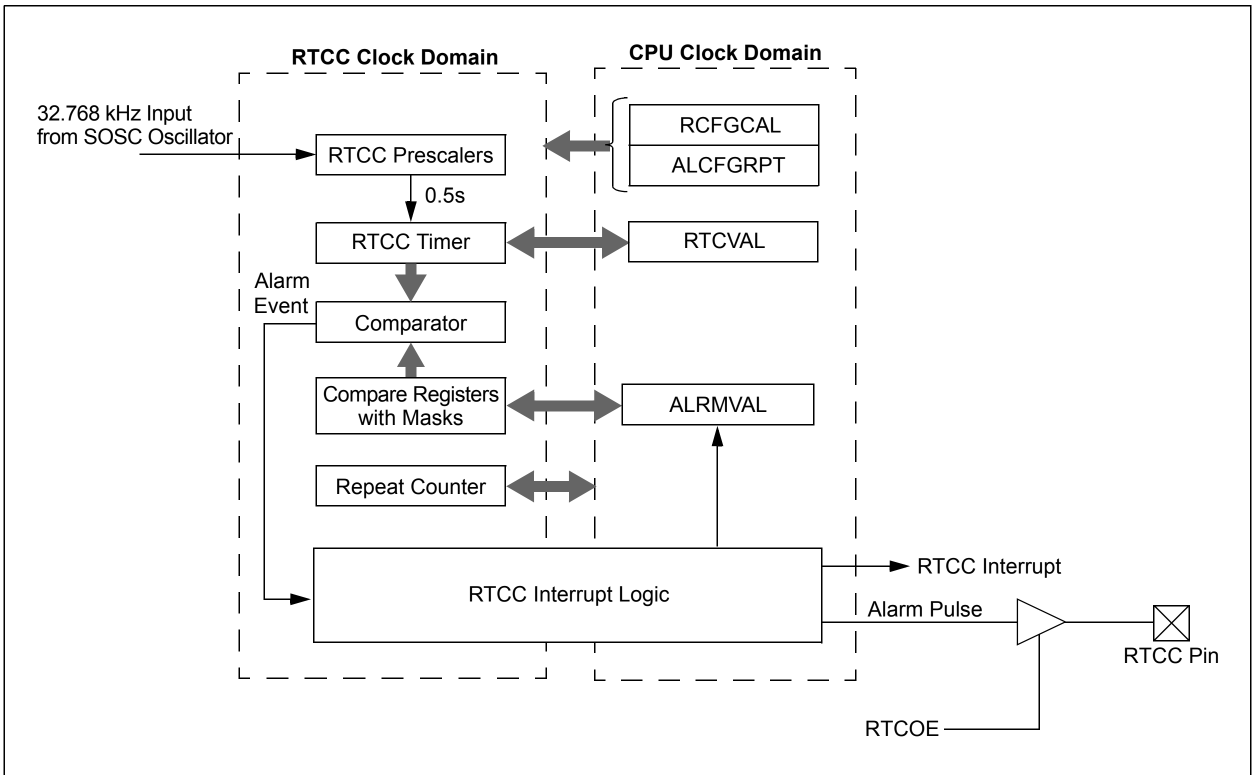
- Time: hours, minutes, and seconds
- 24-hour format (military time)
- Calendar: weekday, date, month and year
- Alarm configurable
- Year range: 2000 to 2099
- Leap year correction
- BCD format for compact firmware
- Optimized for low-power operation
- User calibration with auto-adjust
- Calibration range: ±2.64 seconds error per month
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

The RTCC module is intended for applications where accurate time must be maintained for extended periods of time with minimum to no intervention from the CPU. The RTCC module is optimized for low-power usage to provide extended battery lifetime while keeping track of time.

The RTCC module is a 100-year clock and calendar with automatic leap year detection. The range of the clock is from 00:00:00 (midnight) on January 1, 2000 to 23:59:59 on December 31, 2099.

The hours are available in 24-hour (military time) format. The clock provides a granularity of one second with half-second visibility to the user.

FIGURE 24-1: RTCC BLOCK DIAGRAM



24.3 RTCC Registers

REGISTER 24-1: RCFGCAL: RTCC CALIBRATION AND CONFIGURATION REGISTER(1)

R/W-0	U-0	R/W-0	R-0	R-0	R/W-0	R/W-0	R/W-0
RTCEN(2)	—	RTCWREN	RTCSYNC	HALFSEC(3)	RTCOE	RTCPTR<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CAL<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **RTCEN:** RTCC Enable bit(2)
1 = RTCC module is enabled
0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **RTCWREN:** RTCC Value Registers Write Enable bit
1 = RTCVALH and RTCVALL registers can be written to by the user
0 = RTCVALH and RTCVALL registers are locked out from being written to by the user

bit 12 **RTCSYNC:** RTCC Value Registers Read Synchronization bit
1 = RTCVALH, RTCVALL and ALCFGRPT registers can change while reading due to a rollover ripple resulting in an invalid data read. If the register is read twice and results in the same data, the data can be assumed to be valid.
0 = RTCVALH, RTCVALL or ALCFGRPT registers can be read without concern over a rollover ripple

bit 11 **HALFSEC:** Half-Second Status bit(3)
1 = Second half period of a second
0 = First half period of a second

bit 10 **RTCOE:** RTCC Output Enable bit
1 = RTCC output enabled
0 = RTCC output disabled

bit 9-8 **RTCPTR<1:0>:** RTCC Value Register Window Pointer bits
Points to the corresponding RTCC Value registers when reading RTCVALH and RTCVALL registers; the RTCPTR<1:0> value decrements on every read or write of RTCVALH until it reaches ‘00’.

RTCVAL<15:8>:
00 = MINUTES
01 = WEEKDAY
10 = MONTH
11 = Reserved

RTCVAL<7:0>:
00 = SECONDS
01 = HOURS
10 = DAY
11 = YEAR

Note 1: The RCFGCAL register is only affected by a POR.
2: A write to the RTCEN bit is only allowed when RTCWREN = 1.
3: This bit is read-only. It is cleared to ‘0’ on a write to the lower half of the MINSEC register.

REGISTER 24-10: ALRMVAL (WHEN ALRMPTR<1:0> = 00): ALARM MINUTES AND SECONDS VALUE REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	MINTEN<2:0>			MINONE<3:0>			
bit 15							bit 8

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	SECTEN<2:0>			SECONE<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**Unimplemented:** Read as ‘0’
bit 14-12	**MINTEN<2:0>:** Binary Coded Decimal Value of Minute’s Tens Digit; contains a value from 0 to 5
bit 11-8	**MINONE<3:0>:** Binary Coded Decimal Value of Minute’s Ones Digit; contains a value from 0 to 9
bit 7	**Unimplemented:** Read as ‘0’
bit 6-4	**SECTEN<2:0>:** Binary Coded Decimal Value of Second’s Tens Digit; contains a value from 0 to 5
bit 3-0	**SECONE<3:0>:** Binary Coded Decimal Value of Second’s Ones Digit; contains a value from 0 to 9

TABLE 30-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.[3]	**Typical[2]**	**Max**	**Units**	**Conditions**		
Operating Current (IDD)[1]						
DC20d	18	21	mA	-40°C	3.3V	10 MIPS
DC20a	18	22	mA	+25°C		
DC20b	18	22	mA	+85°C		
DC20c	18	25	mA	+125°C		
DC21d	30	35	mA	-40°C	3.3V	16 MIPS
DC21a	30	34	mA	+25°C		
DC21b	30	34	mA	+85°C		
DC21c	30	36	mA	+125°C		
DC22d	34	42	mA	-40°C	3.3V	20 MIPS
DC22a	34	41	mA	+25°C		
DC22b	34	42	mA	+85°C		
DC22c	35	44	mA	+125°C		
DC23d	49	58	mA	-40°C	3.3V	30 MIPS
DC23a	49	57	mA	+25°C		
DC23b	49	57	mA	+85°C		
DC23c	49	60	mA	+125°C		
DC24d	63	75	mA	-40°C	3.3V	40 MIPS
DC24a	63	74	mA	+25°C		
DC24b	63	74	mA	+85°C		
DC24c	63	76	mA	+125°C		

Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:
- Oscillator is configured in EC mode, no PLL until 10 MIPS, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (defined PMDx bits are set to zero)
- CPU executing `while(1)` statement
- JTAG is disabled

2: Data in “Typ” column is at 3.3V, +25ºC unless otherwise stated.

3: These parameters are characterized but not tested in manufacturing.

TABLE 30-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ[(1)]**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O pins	VSS	—	0.2 VDD	V	
DI11		PMP pins	VSS	—	0.15 VDD	V	PMPTTL = 1
DI15		$\overline{\text{MCLR}}$	VSS	—	0.2 VDD	V	
DI16		I/O Pins with OSC1 or SOSCI	VSS	—	0.2 VDD	V	
DI18		I/O Pins with SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	VSS	—	0.8 VDD	V	SMBus enabled
	VIH	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant[(4)]	0.7 VDD	—	VDD	V	
		I/O Pins 5V Tolerant[(4)]	0.7 VDD	—	5.5	V	
DI21		I/O Pins Not 5V Tolerant with PMP[(4)]	0.24 VDD + 0.8	—	VDD	V	
		I/O Pins 5V Tolerant with PMP[(4)]	0.24 VDD + 0.8	—	5.5	V	
DI28		SDAx, SCLx	0.7 VDD	—	5.5	V	SMBus disabled
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled
	ICNPU	**CNx Pull-up Current**					
DI30			50	250	400	μA	VDD = 3.3V, VPIN = VSS

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See the **“Pin Diagrams”** section for the 5V tolerant I/O pins.

5: VIL source < (VSS – 0.3). Characterized but not tested.

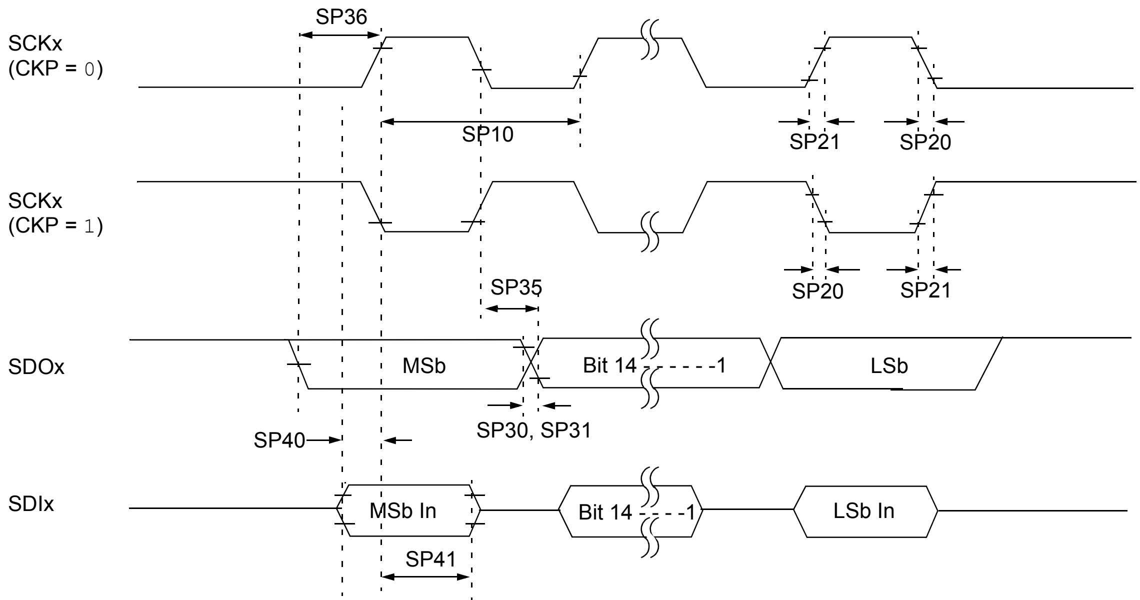
6: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 30-11: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



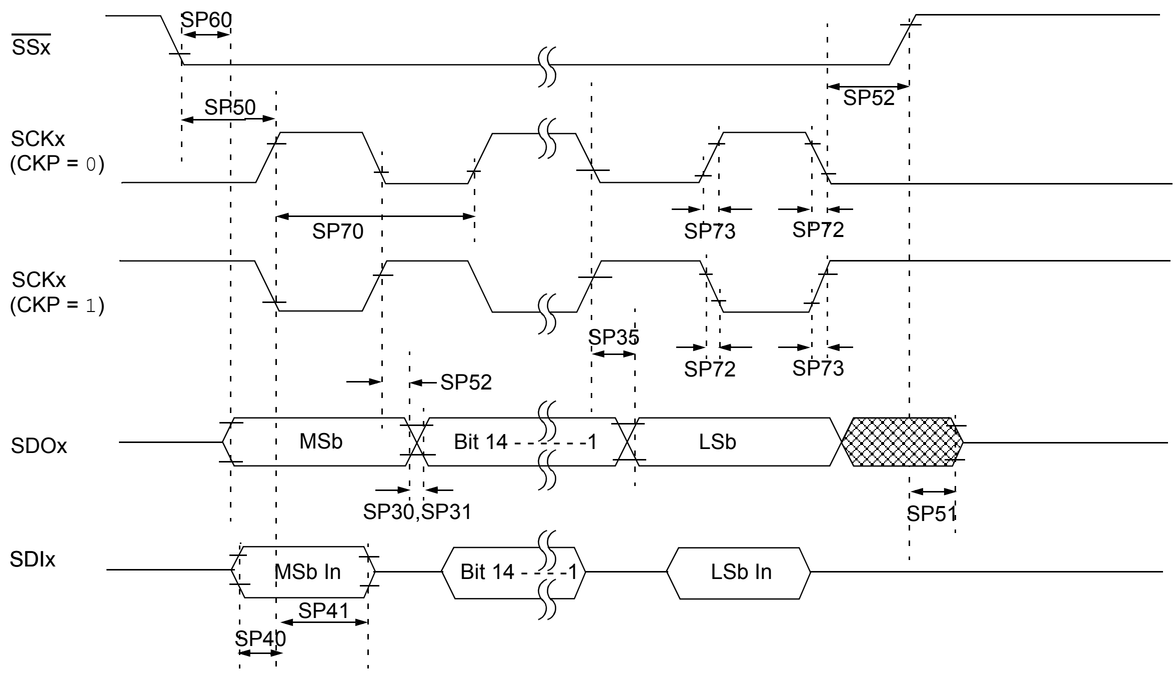
Note: Refer to Figure 30-1 for load conditions.

TABLE 30-30: SPIx MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP10	TscP	Maximum SCK Frequency	—	—	9	MHz	See **Note 3**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—

Note 1: These parameters are characterized, but are not tested in manufacturing.
2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.
3: The minimum clock period for SCKx is 111 ns. The clock generated in Master mode must not violate this specification.
4: Assumes 50 pF load on all SPIx pins.

FIGURE 30-14: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-37: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	**Symbol**	**Characteristic**		**Min**	**Max**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	μs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	μs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode(1)	0	0.3	μs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.25	—	μs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.25	—	μs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	μs	—
			400 kHz mode	0.6	—	μs	
			1 MHz mode(1)	0.6	—	μs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode(1)	250		ns	
IS40	TAA:SCL	Output Valid From Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode(1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode(1)	0.5	—	μs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

FIGURE 30-23: ECAN™ MODULE I/O TIMING CHARACTERISTICS

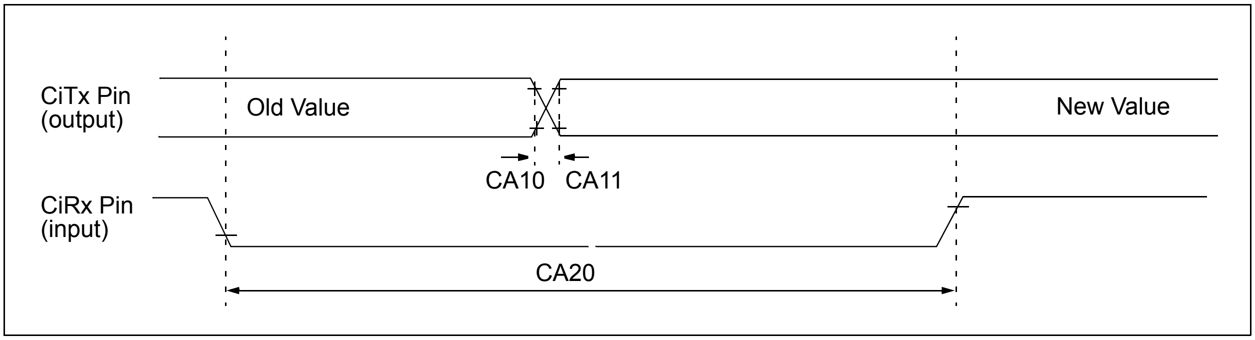


TABLE 30-40: ECAN™ MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
CA10	TioF	Port Output Fall Time	—	—	—	ns	See parameter D032
CA11	TioR	Port Output Rise Time	—	—	—	ns	See parameter D031
CA20	Tcwf	Pulse-Width to Trigger CAN Wake-up Filter	120			ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	Updated Typical values for Thermal Packaging Characteristics (see Table 30-3). Updated Min and Max values for parameter DC12 (RAM Data Retention Voltage) and added Note 4 (see Table 30-4). Updated Power-Down Current Max values for parameters DC60b and DC60c (see Table 30-7). Updated Characteristics for I/O Pin Input Specifications and added parameter DI21 (see Table 30-9). Updated Program Memory values for parameters 136, 137, and 138 (renamed to 136a, 137a, and 138a), added parameters 136b, 137b, and 138b, and added Note 2 (see Table 30-12). Added parameter OS42 (GM) to the External Clock Timing Requirements (see Table 30-16). Updated Watchdog Timer Time-out Period parameter SY20 (see Table 30-21). Updated the IREF Current Drain parameter AD08 (see Table 30-37). Updated parameters AD30a, AD31a, AD32a, AD33a, and AD34a (see Table 30-38) Updated parameters AD30b, AD31b, AD32b, AD33b, and AD34b (see Table 30-39)